

Appl. No. 10/660,866
Response dated March 5, 2005

PATENT

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Amendments to the Claims:

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

Claims 1.-8. (canceled)

Claim 9. (original) A method of making a chip device, the method comprising:

providing a die;

providing a leadframe including a die attach cavity and a plurality of dimples defined around a periphery of the leadframe, the die attach cavity having substantially the same thickness as the die;

placing solder balls into the dimples; and

flipping the die into the die attach cavity and attaching it therein.

Claim 10. (original) The method of claim 9 wherein the die provided is a bumped die.

Claim 11. (previously presented) The method of claim 9 wherein the die comprises a MOSFET.

Claim 12. (previously presented) The method of claim 9 further comprising placing solder on the die.

Claim 13. (previously presented) The method of claim 9 wherein the leadframe comprises a copper based alloy.

Claim 14. (previously presented) The chip device of claim 9 wherein the leadframe includes a solderable coating.

Claim 15. (previously presented) The method of claim 9 wherein the die comprises source and gate connections.

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Claim 16. (previously presented) The method of claim 9 wherein the leadframe comprises a Ni-Pd coating.

Claim 17. (new) The method of claim 9 wherein the die has solder balls thereon to serve as source and gate connections.

Claim 18. (new) The method of claim 9 wherein the step of attaching the die is performed such that the die is coplanar with a top surface of the leadframe.

Claim 19. (new) The method of claim 9 further comprising the step of adding a solderable coating to the leadframe.

Claim 20. (new) The method of claim 9 wherein the leadframe is conductive.

Claim 21. (new) The method of claim 20 wherein the conductive leadframe comprises a copper based alloy.